

ONE SOURCE ONE SOLUTION

The Most Complete Provider of Advanced Microelectronic Services and Component, Die & Wafer Solutions



Die & Wafer Solutions



- › Largest Global Die Distributor
- › Next-Gen Materials: GaN, SiC
- › Die Express Quick Turn Service
- › Wafer Bumping
- › Turnkey Wafer Processing: Wafer Probe, Thinning, Mapping & Inking, Dicing, Pick & Place, Visual Inspection
- › Customized Output: Sawn on Foil, Waffle Tray, Gel Pack, Tape & Reel
- › Long-term Die & Wafer Storage, VMI
- › EOL Die Sustainment Program (EDSP)
- › Element Evaluation and Lot Acceptance Testing

Hi-Rel Products



- › Hermetic: DIP, SOJ, LLC, Gull Wing, QFP, CQFP, CPGA, Metal Can
- › Plastic: CSP, BGA, QFN, ZIP
- › QML Level Packaging
- › Adv. Packaging: SiP, Precision Die Attach, Optoelectronic Assembly
- › Adv. Interconnect: Flip-Chip, 2.5/3DHI, Wafer-Level-Packaging (WLP), RDLs
- › Custom PCBs, MCMs, PEMS, ASICs
- › Turnkey Assembly, Test, and Kitting
- › SMD/5962, COTS, Memory, Logic, Analog, Diodes, RF/Microwave, DC/DC Converters (Hybrids & PCBs), Data Bus Couplers & Harnesses

Advanced Testing & Qualification



- › Electrical & Environmental Testing
- › Device Characterization Testing
- › FPGA, ASIC, RF, Memory, Analog, Logic, Mixed Signal & Discretes
- › DMEA Trusted Source: Comprehensive Test and Process Screening
- › PEMS / COTS Upscreening & Qual, Reliability Testing
- › Adv. Chamberless Burn-in, HTOL/ TOL
- › ESD Characterization
- › Acoustic Microscopy, X-Ray, XRF, PIND, Fine/Gross Leak Testing
- › Counterfeit Mitigation Services

Component Modification



- › Robotic Hot Solder Dip
- › BGA Reballing
- › CGA Attach
- › Lead Attach & Component Preparation
- › Trim & Form, and Reconditioning
- › PCB Solutions: Rework, Repair
- › Component Harvesting
- › Support Solutions: IC Programming, Tape and Reel, 3D Scan, Bake and Package, Marking, Labeling & Kitting,
- › Supplier Managed Inventory (SMI)
- › Serving all Standard Package Types
- › All Facilities are Nadcap Certified

One Source Sustainment Solutions – keeping mission-critical systems & platforms operational

Original Qualified Product

With exclusive access to the broadest supply of die, Microcross will source original qualified parts that have or will become EOL, avoiding costly requalification.

Form-Fit-Function Recreation

When original qualified die or components are not available, Microcross has the expertise to reverse engineer devices and recreate equivalent devices.

Program Sustainment Management

Uninterrupted product supply through BOM monitoring, long term die & wafer storage, and turnkey and supplier managed inventory (SMI)



Facilities & Locations

17 World Class Manufacturing Operations (550,000+ ft²) in North America & Europe. AS9100 & ISO9001 certified.

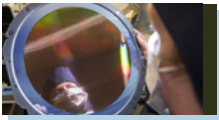
Die & Wafer Solutions



Apopka, FL – Die & Wafer Solutions
Wafer Processing & Test, and Die Distribution



Los Alamitos, CA – SemiDice
Wafer Processing & Test, and Die Distribution



Norwich, UK – Die & Wafer Solutions
Wafer Processing & Test, and Die Distribution



Woburn, MA – Micross Express
Die Distribution, Passive Components, Same-Day Service, & Vendor Managed Inventory

Hi-Rel Products



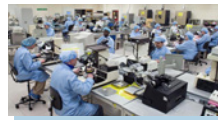
Apopka, FL – Hi-Rel Components
QML Level Packaging, Assembly, Test, and Products



Portchester, UK – Hi-Rel Components
MCM / Hybrid Packaging & Assembly, Test, and Hi-Rel Products



Sunrise, FL – Data Bus Products
Hi-Rel MIL-STD-1553 Data Bus Couplers and Harness Assemblies



Portsmouth, UK – Hi-Rel Components
Hybrid ICs, RF & Microwave Products, Optoelectronics, and PCB Assembly



Shirley, MA – Hi-Rel RF Solutions
GaN/GaAs RF & Microwave Switches, Attenuators & Amplifiers



Reynosa, MX – Hi-Rel Diodes
Hi-Rel Discrete Diodes and Assemblies



San Jose, CA – Hi-Rel Power Solutions
DC-DC Converters, Hybrids and Custom Board Based Power Products



Herlev, DK – Hi-Rel Power Solutions
Design Center for Hi-Rel Power Solutions, and Custom Board Based Power Products

Advanced Testing & Qualification



Milpitas, CA – Silicon Turnkey Solutions
Electrical and Reliability Test, PEMs Upscreening, & Qualification



Manchester, NH – Component Modification
Robotic Hot Solder Dip (RHSD), & Lead Attach / Trim & Form



Raleigh, NC – Adv. Interconnect Technology
Wafer Level Packaging (WLP) & 2.5/3D Heterogeneous Integration



Round Rock, TX – Component Modification
BGA Reballing, Components Harvesting & Reconditioning, and Solderability



Clearwater, FL – Counterfeit Mitigation
Counterfeit Detection Testing, Upscreening, and IC Programming



Crewe, UK – Component Modification
Robotic Hot Solder Dip (RHSD), TCE, BGA Reballing, CGA, and Plating

Corporate Headquarters



Melville, NY
Micross Headquarters

Engineering & Program Management Support

Micross' highly experienced global field sales, and expert engineering teams provide complete application support from design specification to post production sustainment & program management.

Micross Heritage

With over 40+ years experience, Micross has strengthened its' capabilities to offer the broadest microelectronic solutions available from One Source.



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